

Substitute form 1449A/PTO

Complete if Known

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet

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of

7

Application Number

10/780,529

Filing Date

February 17, 2004

First Named Inventor

Jong-Rong Jan

Group Art Unit

2818

Examiner Name

Chuong A. Luu

Attorney Docket Number

9180-30

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Date Considered

01/06/2006

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)			Application Number	10/780,529	
			Filing Date	February 17, 2004	
			First Named Inventor	Jong-Rong Jan	
			Group Art Unit	2818	
			Examiner Name	Chuong A. Luu	
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			Examiner Name	Chuong A. Luu	
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(use as many sheets as necessary)			Attorney Docket Number	9180-30
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Examiner Signature		Date Considered	01/06/2006
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Substitute form 1449A/PTO				Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)				Application Number	10/780,529
				Filing Date	February 17, 2004
				First Named Inventor	Jong-Rong Jan
				Group Art Unit	2818
				Examiner Name	Chuong A. Luu
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